## **INTEGRATED CIRCUITS**

## DATA SHEET



# **74F08**Quad two-input AND gate

Product specification

1995 Apr 19

IC15 Data Handbook

## **Philips Semiconductors**





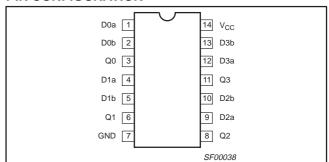
## **Quad 2-input AND gate**

74F08

74F08 Available for industrial range (−40°C to +85°C)

TYPE	TYPICAL PROPAGATION DELAY	TYPICAL SUPPLY CURRENT (TOTAL)
74F08	4.1ns	7.1mA

#### **PIN CONFIGURATION**



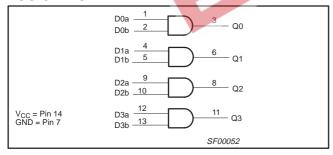
#### **ORDERING INFORMATION**

DESCRIPTION	COMMERCIAL RANGE $V_{CC} = 5.0V \pm 10\%, T_{amb} = 0^{\circ}\text{C to } +70^{\circ}\text{C}$	INDUSTRIAL RANGE $V_{CC}$ = 5.0V $\pm 10\%$ , $T_{amb}$ = $-40^{\circ}$ C to +85°C	PKG DWG #
14-pin plastic DIP	N74F08N	174F08N	SOT27-1
14-pin plastic SO	N74F08D	17 <b>4</b> F08D	SOT108-1

14-pin plasti	0.50	197	41 00D		1141 000	301100-1
INPUT AND	OUTP	JT LOADING AI	ND FAN-OUT TABL	É	& 3 m.C.	
PINS	}	D	ESCRIPTION		74F (U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW
Dna, D	nb	Data inputs			1.0/1.0	20μA/0.6mA
Qn		Data output			50/33	1.0mA/20mA

NOTE: One (1.0) FAST unit load is defined as: 20µA in the High state and 0.6mA in the Low state.

#### **LOGIC DIAGRAM**



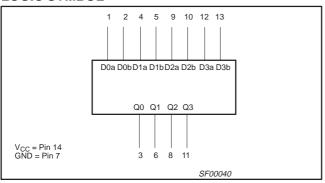
#### **FUNCTION TABLE**

INP	UTS	OUTPUT
Dna	Dnb	Qn
L	L	L
L	Н	L
Н	L	L
Н	Н	Н

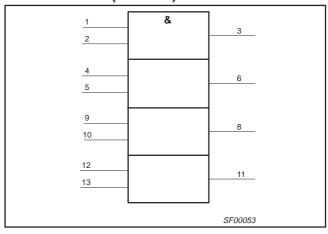
#### NOTES:

H = High voltage level L = Low voltage level

#### **LOGIC SYMBOL**



#### LOGIC SYMBOL (IEEE/IEC)



### Quad 2-input AND gate

74F08

#### **ABSOLUTE MAXIMUM RATINGS**

(Operation beyond the limits set forth in this table may impair the useful life of the device. Unless otherwise noted these limits are over the operating free-air temperature range.)

SYMBOL	PARAMETER		RATING	UNIT					
V <sub>CC</sub>	Supply voltage		-0.5 to +7.0	V					
V <sub>IN</sub>	Input voltage	nput voltage							
I <sub>IN</sub>	Input current	-30 to +5	mA						
V <sub>OUT</sub>	Voltage applied to output in High output state	–0.5 to V <sub>CC</sub>	V						
l <sub>OUT</sub>	Current applied to output in Low output state		40	mA					
_		Commercial range	0 to +70	°C					
l <sub>amb</sub>	Operating free-air temperature range	-40 to +85	°C						
T <sub>stg</sub>	Storage temperature range	-65 to +150	°C						

#### RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER		4 14 14	LIMITS		UNIT
STWIBUL	PARAMETER	. 36.	MIN	NOM	MAX	UNII
V <sub>CC</sub>	Supply voltage	20 3	4.5	5.0	5.5	V
$V_{lh}$	High-level input voltage	1.35	2.0			V
$V_{IL}$	Low-level input voltage				0.8	V
I <sub>IK</sub>	Input clamp current				-18	mA
I <sub>OH</sub>	High-level output current				-1	mA
I <sub>OL</sub>	Low-level output current				20	mA
т.	Operating free-air temperature range	Commercial range	0		+70	°C
lamb	Operating nee-an temperature range	Industrial range	-40		+85	°C

3.

#### DC ELECTRICAL CHARACTERISTICS

(Over recommended operating free-air temperature range unless otherwise noted.)

OVMDOL	DADAMETER		TEGT CONDITIO	NO1		LIMITS		
SYMBOL	PARAMETER		TEST CONDITIO	'SNO	MIN	TYP <sup>2</sup>	MAX	UNIT
V	High lovel output voltage		$V_{CC} = MIN, V_{IL} = MAX$	±10%V <sub>CC</sub>	2.5			V
V <sub>OH</sub>	High-level output voltage		$V_{IH} = MIN, I_{OH} = MAX$	±5%V <sub>CC</sub>	2.7	3.4		V
\/	Low lovel output voltage		$V_{CC} = MIN, V_{IL} = MAX$	±10%V <sub>CC</sub>		0.30	0.50	V
V <sub>OL</sub>	Low-level output voltage		$V_{IH} = MIN, I_{OI} = MAX$	±5%V <sub>CC</sub>		0.30	0.50	V
$V_{IK}$	Input clamp voltage		$V_{CC} = MIN, I_I = I_{IK}$		-0.73	-1.2	V	
I <sub>I</sub>	Input current at maximum voltage	input	$V_{CC} = MAX, V_I = 7.0V$				100	μА
I <sub>IH</sub>	High-level input current		$V_{CC} = MAX, V_I = 2.7V$				20	μΑ
I <sub>IL</sub>	Low-level input current		$V_{CC} = MAX, V_I = 0.5V$				-0.6	mA
los	Short-circuit output currer	nt <sup>3</sup>	$V_{CC} = MAX$		-60		-150	mA
	Cumply ourrent (total)		$V_{CC} = MAX$	V <sub>IN</sub> = 4.5V		5.5	8.3	mA
Icc	Supply current (total)		V <sub>CC</sub> = MAX	V <sub>IN</sub> = GND		8.6	12.9	mA

#### NOTES:

- 1. For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.
- All typical values are at V<sub>CC</sub> = 5V, T<sub>amb</sub> = 25°C.
  Not more than one output should be shorted at a time. For testing I<sub>OS</sub>, the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a High output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I<sub>OS</sub> tests should be performed last.

1995 Apr 19 3

## Quad 2-input AND gate

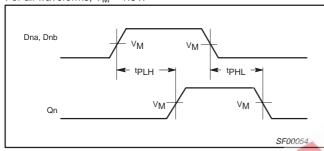
74F08

#### **AC ELECTRICAL CHARACTERISTICS**

						LIM	ITS			
SYMBOL	PARAMETER	TEST CONDITION	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	<sub>mb</sub> = +25 <sub>CC</sub> = +5.0 C <sub>L</sub> = 50pF R <sub>L</sub> = 5009	)V <del>-</del> ,	V <sub>CC</sub> = +5. C <sub>L</sub> =	C to +70°C 0V ± 10% 50pF, 500Ω	T <sub>amb</sub> = -40° V <sub>CC</sub> = +5. C <sub>L</sub> = 8 R <sub>L</sub> =	UNIT	
			MIN	MIN TYP MA		MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	Propagation delay Dna, Dnb to Qn	Waveform 1	3.0 2.5	4.2 4.0	5.6 5.3	3.0 2.5	6.6 6.3	2.5 2.5	6.6 6.3	ns

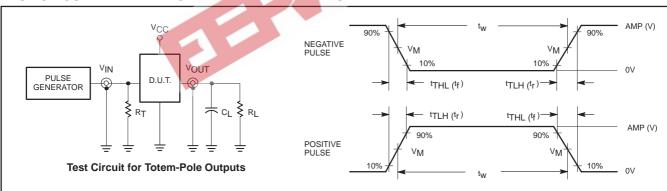
#### **AC WAVEFORMS**

For all waveforms,  $V_M = 1.5V$ .



Waveform 1. Propagation Delay for Non-Inverting Outputs

#### **TEST CIRCUIT AND WAVEFORM**



#### **DEFINITIONS:**

R<sub>L</sub> = Load resistor;

see AC ELECTRICAL CHARACTERISTICS for value.

C<sub>L</sub> = Load capacitance includes jig and probe capacitance; see AC ELECTRICAL CHARACTERISTICS for value.

Termination resistance should be equal to Z<sub>OUT</sub> of pulse generators.

#### Input Pulse Definition

family	INP	INPUT PULSE REQUIREMENTS											
family	amplitude	$V_{\text{M}}$	rep. rate	t <sub>w</sub>	t <sub>TLH</sub>	t <sub>THL</sub>							
74F	3.0V 1.5		1MHz	500ns	2.5ns	2.5ns							

SF00006

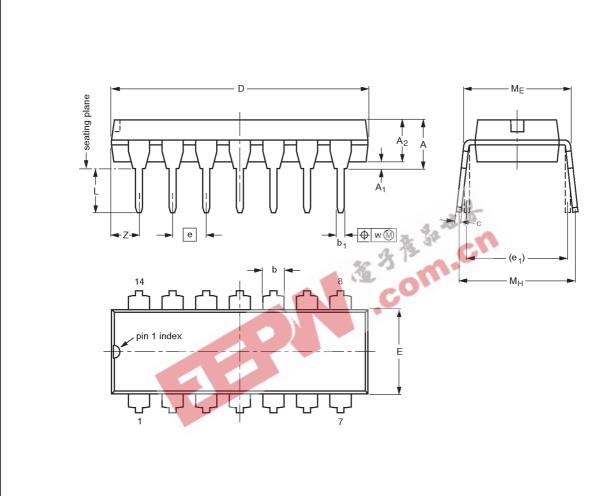
4 1995 Apr 19

## Quad 2-input AND gate

74F08

#### DIP14: plastic dual in-line package; 14 leads (300 mil)

SOT27-1





#### DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A <sub>1</sub> min.	A <sub>2</sub> max.	b	b <sub>1</sub>	С	D <sup>(1)</sup>	E <sup>(1)</sup>	е	e <sub>1</sub>	L	ME	M <sub>H</sub>	w	Z <sup>(1)</sup> max.
mm	4.2	0.51	3.2	1.73 1.13	0.53 0.38	0.36 0.23	19.50 18.55	6.48 6.20	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.2
inches	0.17	0.020	0.13	0.068 0.044	0.021 0.015	0.014 0.009	0.77 0.73	0.26 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.087

#### Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE	
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE
SOT27-1	050G04	MO-001AA			<del>92-11-17</del> 95-03-11

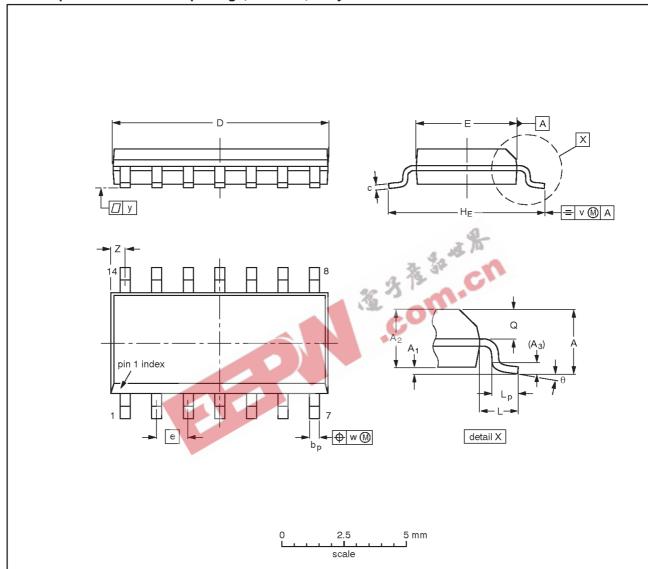
1995 Apr 19 5

## Quad 2-input AND gate

74F08

#### SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1



#### DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	bp	С	D <sup>(1)</sup>	E <sup>(1)</sup>	е	HE	L	Lp	Q	v	w	у	Z <sup>(1)</sup>	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	8.75 8.55	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8°
inches	0.069	0.010 0.004	0.057 0.049	0.01		0.0100 0.0075	0.35 0.34	0.16 0.15	0.050	0.244 0.228	0.041	0.039 0.016	0.028 0.024	0.01	0.01	0.004	0.028 0.012	0°

#### Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE	REFERENCES				EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT108-1	076E06S	MS-012AB				<del>95-01-23</del> 97-05-22

1995 Apr 19 6

## Quad 2-input AND gate

74F08

#### **NOTES**



1995 Apr 19 7

#### Quad 2-input AND gate

74F08

#### Data sheet status

Data sheet status	Product status	Definition [1]	
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.	
Preliminary specification	Qualification	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make chages at any time without notice in order to improve design and supply the best possible product.	
Product specification	Production	This data sheet contains final specifications. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.	

<sup>[1]</sup> Please consult the most recently issued datasheet before initiating or completing a design.

#### **Definitions**

**Short-form specification** — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

**Application information** — Applications that are described herein for any of these products are for illustrative purposes only. Philips Semiconductors make no representation or warranty that such applications will be suitable for the specified use without further testing or modification.

#### **Disclaimers**

**Life support** — These products are not designed for use in life support appliances, devices or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips Semiconductors customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips Semiconductors for any damages resulting from such application.

Right to make changes — Philips Semiconductors reserves the right to make changes, without notice, in the products, including circuits, standard cells, and/or software, described or contained herein in order to improve design and/or performance. Philips Semiconductors assumes no responsibility or liability for the use of any of these products, conveys no license or title under any patent, copyright, or mask work right to these products, and makes no representations or warranties that these products are free from patent, copyright, or mask work right infringement, unless otherwise specified.

Philips Semiconductors 811 East Arques Avenue P.O. Box 3409 Sunnyvale, California 94088–3409 Telephone 800-234-7381 © Copyright Philips Electronics North America Corporation 1998 All rights reserved. Printed in U.S.A.

print code Date of release: 10-98

Document order number: 9397-750-05055

Let's make things better.



